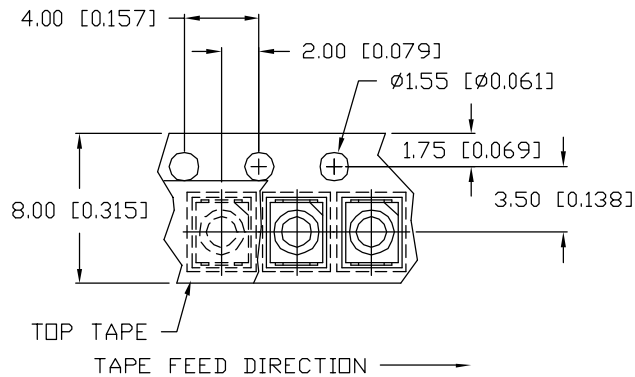
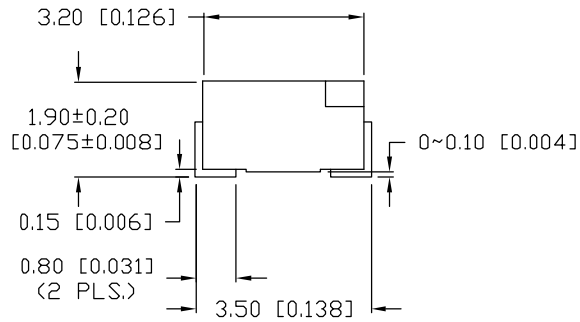
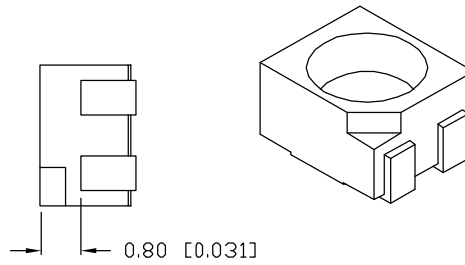
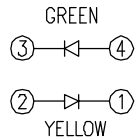
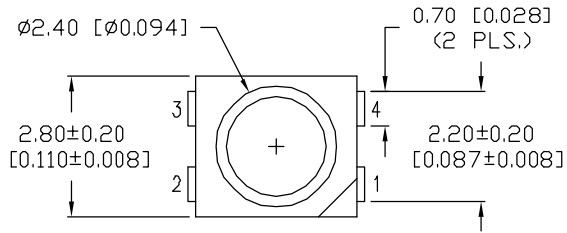


UNCONTROLLED DOCUMENT



REPLACES PART #: SML-LX2832YGC(-TR)

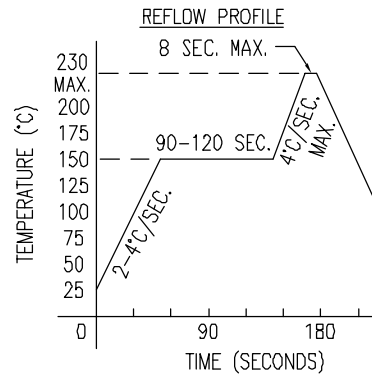
*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

PART NUMBER		REV.
SML-LX2832YGC-TR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03

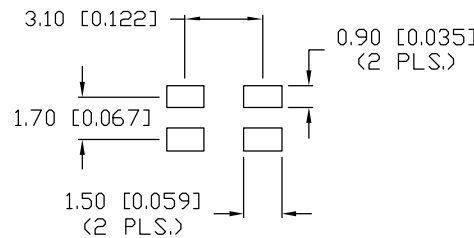
ELECTRO-OPTICAL CHARACTERISTICS TA=25°C If=20mA					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (YELLOW)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE		2.1/2.2	2.5/2.6	Vf	
REVERSE VOLTAGE	5.0			Vr	Ir=100µA
AXIAL INTENSITY (Y/G)		15/25		mcd	If=20mA
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	YELLOW/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP			
PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT	(Y/G)	30/25	mA
POWER DISSIPATION		100	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-25 TO +85	°C
STORAGE TEMP.		-30 TO +85	°C

* t<10µS



RECOMMENDED SOLDER PAD LAYOUT



NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
A	SML-LX2832YGC-TR

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290 E. HELLEN ROAD
PALATINE, ILLINOIS 60067
PHONE: (847) 359-2790
WEB: <http://www.lumex.com>

2.8mm x 3.2mm SURFACE MOUNT WITH REFLECTOR CUP, DUAL CHIP, 585nm YELLOW LED AND 565nm GREEN LED, WATER CLEAR LENS, 2k PER REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 12.11.00
BC			PAGE: 1 OF 1
			SCALE: N/A